

Achieved Fast Cure for In-Line Process as well as Excellent Fillings and Applicable from Insertion Type to Surface Mount Type.

Strong Points

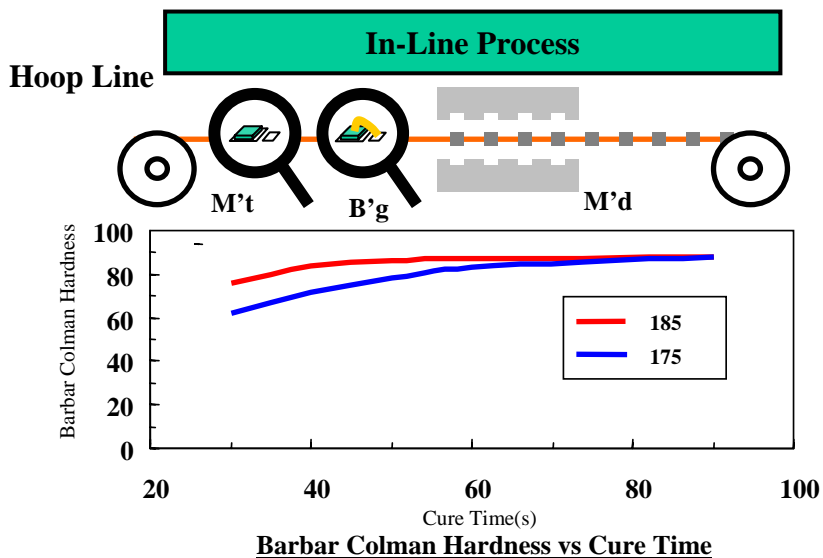
- a) Achieve Good and Necessary Filling in KE-520Series to Apply to Ultra Small Packages.
- b) JEDEC level 1 is Possible in Ultra Small Packages.
- c) Good Adhesion Strength Even after High Temperature Reflow Soldering Process.
- d) Fast Cure Enabling High Productive In-Line Auto Process.
- e) Excellent moldability and show improvement in moldability yield.

Application

• Surface Mount Device • TO-92 Type (Insertion Type) • Ultrasmall PKG

General Properties

Items	unit	KE-520TD-2	KE-300K
Spiral Flow	cm	100	100
Gel Time	s	20	27
Specific Gravity	-	1.9	1.8
Glass Transition Temp.	°C	175	180
C.T.E	α1	1.5	1.8
	α2	6.0	6.7
Application	-	Surface Mount Device	Insertion Type



Typical Application

